



Docket No.: 042390.P7045D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Ramalingam, et al.

Application No.: 09/874,666

Filed: June 5, 2001

For: A Controlled Collapse Chip  
Connection (C4) Integrated Circuit  
Package Which Has Two Dissimilar  
Underfill Materials

Examiner: David E. Graybill

Art Group: 2827

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PRELIMINARY AMENDMENT

BOX RCE  
Assistant Commissioner for Patents  
Washington, DC 20231-9998

Sir:

Please amend the above-identified Application as follows:

IN THE CLAIMS

Following is a complete set of claims as amended with this Response. This complete set of claims excludes claims 7-14 and 26-30, cancelled without prejudice, and requests examination of new claims 31-48.

- 1 31. (New) An integrated circuit package comprising:
- 2 a substrate;
- 3 an integrated circuit attached to the substrate;
- 4 a first material dispensed at a first temperature between the substrate and the integrated
- 5 circuit as underfill; and

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WWS/crr  
Filed: 6/5/01

NOT  
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